

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHANG-CHEN TSAO	03/07/2018
KUO LIANG LU	03/13/2018
RU-LIANG LEE	03/06/2018
SHENG-HSIANG CHUANG	03/09/2018
YU-HUNG CHENG	03/09/2018
YEUR-LUEN TU	03/15/2018
CHENG-KANG HU	03/09/2018
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16220163
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PATENT

DATE SIGNED:	12/14/2018
Total Attachments: 9 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif source=Assignment#page8.tif source=Assignment#page9.tif	

LL
(P)

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Chang-Chen Tsao

Assignor(s):

Kuo Liang Lu

Assignor(s):

Ru-Liang Lee

Assignor(s):

Sheng-Hsiang Chuang

Assignor(s):

Yu-Hung Cheng

Assignor(s):

Yeur-Luen Tu

Assignor(s):

Cheng-Kang Hu

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
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Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"WAFER DEBONDING SYSTEM AND METHOD" for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this

Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

TSMC Docket No. P20160997US00
Docket No. TSMCP780US

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2018-03-07
Date

Chang-Chen Tsao
Name 1st Inventor Chang-Chen Tsao

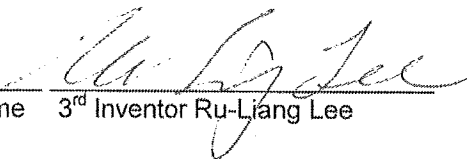
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Docket No. TSMCP780US

2018/3/13
Date

Kuo Liang Lu
Name 2nd Inventor Kuo Liang Lu

TSMC Docket No. P20160997US00
Docket No. TSMCP780US

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Date


Name 3rd Inventor Ru-Liang Lee

TSMC Docket No. P20160997US00
Docket No. TSMCP780US

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Date

Sheng-Hsiang Chuang.
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TSMC Docket No. P20160997US00
Docket No. TSMCP780US

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Date

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TSMC Docket No. P20160997US00
Docket No. TSMCP780US

2018/3/15
Date

Y-L Tu
Name 6th Inventor Yeur-Luen Tu

TSMC Docket No. P20160997US00
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2018.03.09
Date

Cheng-Kang Hu
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